

# LTC2605/LTC2615/LTC2625

## ABSOLUTE MAXIMUM RATINGS (Note 1)

Any Pin to GND .....	-0.3V to 6V	Operating Temperature Range	
Any Pin to $V_{CC}$ .....	-6V to 0.3V	LTC2605C/LTC2615C/LTC2625C .....	0°C to 70°C
Maximum Junction Temperature .....	125°C	LTC2605C-1/LTC2615C-1/LTC2625C-1 ...	0°C to 70°C
Storage Temperature Range .....	-65°C to 150°C	LTC2605I/LTC2615I/LTC2625I .....	-40°C to 85°C
Lead Temperature (Soldering, 10 sec) .....	300°C	LTC2605I-1/LTC2615I-1/LTC2625I-1 ..	-40°C to 85°C

## PACKAGE/ORDER INFORMATION

	ORDER PART NUMBER	GN PART MARKING
		LTC2605CGN
	LTC2605CGN-1	26051
	LTC2605IGN	2605I
	LTC2605IGN-1	2605I1
	LTC2615CGN	2615
	LTC2615CGN-1	26151
	LTC2615IGN	2615I
	LTC2615IGN-1	2615I1
	LTC2625CGN	2625
	LTC2625CGN-1	26251
	LTC2625IGN	2625I
	LTC2625IGN-1	2625I1

Consult LTC Marketing for parts specified with wider operating temperature ranges.

## ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ .  $V_{REF} = 4.096\text{V}$  ( $V_{CC} = 5\text{V}$ ),  $V_{REF} = 2.048\text{V}$  ( $V_{CC} = 2.7\text{V}$ ),  $V_{OUT}$  unloaded, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	LTC2625/-1			LTC2615/-1			LTC2605/-1			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>DC Performance</b>												
	Resolution		●	12		14		16				Bits
	Monotonicity	(Note 2)	●	12		14		16				Bits
DNL	Differential Nonlinearity	(Note 2)	●		±0.5		±1		±1			LSB
INL	Integral Nonlinearity	(Note 2)	●		±1 ±4		±4 ±16		±18 ±64			LSB
	Load Regulation	$V_{REF} = V_{CC} = 5\text{V}$ , Midscale										
		$I_{OUT} = 0\text{mA}$ to 15mA Sourcing	●	0.02	0.125		0.07	0.5		0.3	2	LSB/mA
		$I_{OUT} = 0\text{mA}$ to 15mA Sinking	●	0.03	0.125		0.10	0.5		0.4	2	LSB/mA
		$V_{REF} = V_{CC} = 2.7\text{V}$ , Midscale										
		$I_{OUT} = 0\text{mA}$ to 7.5mA Sourcing	●	0.04	0.25		0.15	1		0.6	4	LSB/mA
		$I_{OUT} = 0\text{mA}$ to 7.5mA Sinking	●	0.07	0.25		0.20	1		0.8	4	LSB/mA
ZSE	Zero-Scale Error	Code = 0	●	1.7	9		1.7	9		1.7	9	mV
$V_{OS}$	Offset Error	(Note 4)	●	±1	±9		±1	±9		±1	±9	mV
	$V_{OS}$ Temperature Coefficient			±5			±5		±5			$\mu\text{V}/^\circ\text{C}$
GE	Gain Error		●	±0.1	±0.7		±0.1	±0.7		±0.1	±0.7	%FSR
	Gain Temperature Coefficient			±8			±8		±8			ppm/ $^\circ\text{C}$

2605f

## ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . REF = 4.096V ( $V_{CC} = 5\text{V}$ ), REF = 2.048V ( $V_{CC} = 2.7\text{V}$ ),  $V_{OUT}$  unloaded, unless otherwise noted. (Note 9)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
PSR	Power Supply Rejection	$V_{CC} \pm 10\%$		-80		dB	
$R_{OUT}$	DC Output Impedance	$V_{REF} = V_{CC} = 5\text{V}$ , Midscale; $-15\text{mA} \leq I_{OUT} \leq 15\text{mA}$	●	0.02	0.15	$\Omega$	
		$V_{REF} = V_{CC} = 2.7\text{V}$ , Midscale; $-7.5\text{mA} \leq I_{OUT} \leq 7.5\text{mA}$	●	0.03	0.15	$\Omega$	
	DC Crosstalk (Note 10)	Due to Full Scale Output Change (Note 11) Due to Load Current Change Due to Powering Down (per Channel)		$\pm 10$ $\pm 3.5$ $\pm 7$		$\mu\text{V}$ $\mu\text{V}/\text{mA}$ $\mu\text{V}$	
$I_{SC}$	Short-Circuit Output Current	$V_{CC} = 5.5\text{V}$ , $V_{REF} = 5.5\text{V}$ Code: Zero Scale; Forcing Output to $V_{CC}$ Code: Full Scale; Forcing Output to GND	●	15	34	60	mA
			●	15	34	60	mA
		$V_{CC} = 2.7\text{V}$ , $V_{REF} = 2.7\text{V}$ Code: Zero Scale; Forcing Output to $V_{CC}$ Code: Full Scale; Forcing Output to GND	●	7.5	20	50	mA
			●	7.5	27	50	mA

### Reference Input

	Input Voltage Range		●	0		$V_{CC}$	V
	Resistance	Normal Mode	●	11	16	20	k $\Omega$
	Capacitance				90		pF
$I_{REF}$	Reference Current, Power Down Mode	DAC Powered Down	●		0.001	1	$\mu\text{A}$

### Power Supply

$V_{CC}$	Positive Supply Voltage	For Specified Performance	●	2.7		5.5	V
$I_{CC}$	Supply Current	$V_{CC} = 5\text{V}$ (Note 3)	●		2.50	4.0	mA
		$V_{CC} = 3\text{V}$ (Note 3)	●		2.00	3.2	mA
		DAC Powered Down (Note 3) $V_{CC} = 5\text{V}$	●		0.38	1.0	$\mu\text{A}$
		DAC Powered Down (Note 3) $V_{CC} = 3\text{V}$	●		0.16	1.0	$\mu\text{A}$

### Digital I/O (Note 9)

$V_{IL}$	Low Level Input Voltage (SDA and SCL)		●			$0.3V_{CC}$	V
$V_{IH}$	High Level Input Voltage (SDA and SCL)		●	$0.7V_{CC}$			V
$V_{IL(CA)}$	Low Level Input Voltage (CA0 to CA2)	See Test Circuit 1	●			$0.15V_{CC}$	V
$V_{IH(CA)}$	High Level Input Voltage (CA0 to CA2)	See Test Circuit 1	●	$0.85V_{CC}$			V
$R_{INH}$	Resistance from $CA_n$ ( $n = 0, 1, 2$ ) to $V_{CC}$ to Set $CA_n = V_{CC}$	See Test Circuit 2	●			10	k $\Omega$
$R_{INL}$	Resistance from $CA_n$ ( $n = 0, 1, 2$ ) to GND to Set $CA_n = \text{GND}$	See Test Circuit 2	●			10	k $\Omega$
$R_{INF}$	Resistance from $CA_n$ ( $n = 0, 1, 2$ ) to $V_{CC}$ or GND to Set $CA_n = \text{FLOAT}$	See Test Circuit 2	●	2			M $\Omega$
$V_{OL}$	Low Level Output Voltage	Sink Current = 3mA	●	0		0.4	V
$t_{OF}$	Output Fall Time	$V_O = V_{IH(MIN)}$ to $V_O = V_{IL(MAX)}$ , $C_B = 10\text{pF}$ to 400pF (Note 7)	●	$20 + 0.1C_B$		250	ns
$t_{SP}$	Pulse Width of Spikes Surpassed by Input Filter		●	0		50	ns
$I_{IN}$	Input Leakage	$0.1V_{CC} \leq V_{IN} \leq 0.9V_{CC}$	●			1	$\mu\text{A}$
$C_{IN}$	I/O Pin Capacitance	(Note 12)	●			10	pF
$C_B$	Capacitance Load for Each Bus Line		●			400	pF
$C_{CA_n}$	External Capacitive Load on Address Pins CA0, CA1 and CA2		●			10	pF

# LTC2605/LTC2615/LTC2625

## ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ .  $V_{REF} = 4.096\text{V}$  ( $V_{CC} = 5\text{V}$ ),  $V_{REF} = 2.048\text{V}$  ( $V_{CC} = 2.7\text{V}$ ),  $V_{OUT}$  unloaded, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	LTC2625/-1			LTC2615/-1			LTC2605/-1			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>AC Performance</b>												
$t_S$	Settling Time (Note 5)	$\pm 0.024\%$ ( $\pm 1\text{LSB}$ at 12 Bits)	7			7			7			$\mu\text{s}$
		$\pm 0.006\%$ ( $\pm 1\text{LSB}$ at 14 Bits)				9			9			$\mu\text{s}$
		$\pm 0.0015\%$ ( $\pm 1\text{LSB}$ at 16 Bits)							10			$\mu\text{s}$
	Settling Time for 1LSB Step (Note 6)	$\pm 0.024\%$ ( $\pm 1\text{LSB}$ at 12 Bits)	2.7			2.7			2.7			$\mu\text{s}$
		$\pm 0.006\%$ ( $\pm 1\text{LSB}$ at 14 Bits)				4.8			4.8			$\mu\text{s}$
		$\pm 0.0015\%$ ( $\pm 1\text{LSB}$ at 16 Bits)							5.2			$\mu\text{s}$
	Voltage Output Slew Rate		0.80			0.80			0.80			$\text{V}/\mu\text{s}$
	Capacitive Load Driving		1000			1000			1000			$\text{pF}$
	Glitch Impulse	At Midscale Transition	12			12			12			$\text{nV} \cdot \text{s}$
	Multiplying Bandwidth		180			180			180			$\text{kHz}$
$e_n$	Output Voltage Noise Density	At $f = 1\text{kHz}$	120			120			120			$\text{nV}/\sqrt{\text{Hz}}$
		At $f = 10\text{kHz}$	100			100			100			$\text{nV}/\sqrt{\text{Hz}}$
	Output Voltage Noise	0.1Hz to 10Hz	15			15			15			$\mu\text{V}_{\text{P-P}}$

## TIMING CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (See Figure 1) (Notes 8, 9)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b><math>V_{CC} = 2.7\text{V}</math> to <math>5.5\text{V}</math></b>						
$f_{\text{SCL}}$	SCL Clock Frequency		●	0	400	$\text{kHz}$
$t_{\text{HD(STA)}}$	Hold Time (Repeated) Start Condition		●	0.6		$\mu\text{s}$
$t_{\text{LOW}}$	Low Period of the SCL Clock Pin		●	1.3		$\mu\text{s}$
$t_{\text{HIGH}}$	High Period of the SCL Clock Pin		●	0.6		$\mu\text{s}$
$t_{\text{SU(STA)}}$	Set-Up Time for a Repeated Start Program		●	0.6		$\mu\text{s}$
$t_{\text{HD(DAT)}}$	Data Hold Time		●	0	0.9	$\mu\text{s}$
$t_{\text{SU(DAT)}}$	Data Set-Up Time		●	100		$\text{ns}$
$t_r$	Rise Time of Both SDA and SCL Signals	(Note 7)	●	$20 + 0.1C_B$	300	$\text{ns}$
$t_f$	Fall Time of Both SDA and SCL Signals	(Note 7)	●	$20 + 0.1C_B$	300	$\text{ns}$
$t_{\text{SU(STO)}}$	Set-Up Time for Stop Condition		●	0.6		$\mu\text{s}$
$t_{\text{BUF}}$	Bus Free Time Between a Stop and Start Condition		●	1.3		$\mu\text{s}$

**Note 1:** Absolute maximum ratings are those values beyond which the life of a device may be impaired.

**Note 2:** Linearity and monotonicity are defined from code  $k_L$  to code  $2^N - 1$ , where  $N$  is the resolution and  $k_L$  is given by  $k_L = 0.016(2^N/V_{REF})$ , rounded to the nearest whole code. For  $V_{REF} = 4.096\text{V}$  and  $N = 16$ ,  $k_L = 256$  and linearity is defined from code 256 to code 65,535.

**Note 3:** SDA, SCL at 0V or  $V_{CC}$ , CA0, CA1 and CA2 floating.

**Note 4:** Inferred from measurement at code 256 (LTC2605/LTC2605-1), code 64 (LTC2615/LTC2615-1) or code 16 (LTC2625/LTC2625-1) and at full scale.

**Note 5:**  $V_{CC} = 5\text{V}$ ,  $V_{REF} = 4.096\text{V}$ . DAC is stepped 1/4 scale to 3/4 scale and 3/4 scale to 1/4 scale. Load is  $2\text{k}\Omega$  in parallel with  $200\text{pF}$  to GND.

**Note 6:**  $V_{CC} = 5\text{V}$ ,  $V_{REF} = 4.096\text{V}$ . DAC is stepped  $\pm 1\text{LSB}$  between half scale and half scale - 1. Load is  $2\text{k}\Omega$  in parallel with  $200\text{pF}$  to GND.

**Note 7:**  $C_B$  = capacitance of one bus line in  $\text{pF}$ .

**Note 8:** All values refer to  $V_{IH(\text{MIN})}$  and  $V_{IL(\text{MAX})}$  levels.

**Note 9:** These specifications apply to LTC2605/LTC2605-1, LTC2615/LTC2615-1 and LTC2625/LTC2625-1.

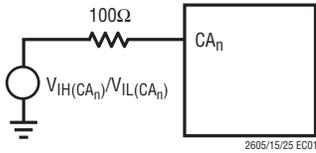
**Note 10:** DC Crosstalk is measured with  $V_{CC} = 5\text{V}$  and  $V_{REF} = 4.096\text{V}$ , with the measured DAC at midscale, unless otherwise noted.

**Note 11:**  $R_L = 2\text{k}\Omega$  to GND or  $V_{CC}$ .

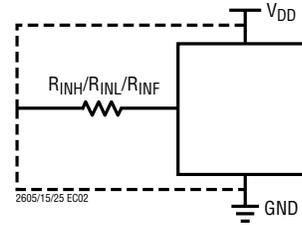
**Note 12:** Guaranteed by design and not production tested.

# ELECTRICAL CHARACTERISTICS

Test Circuit 1



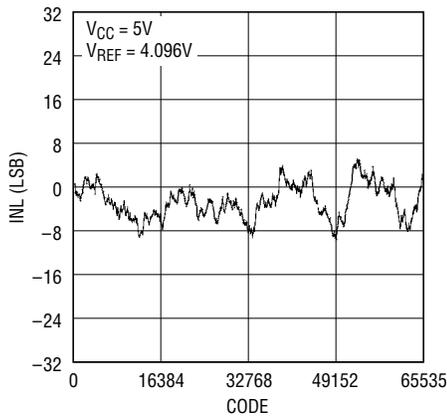
Test Circuit 2



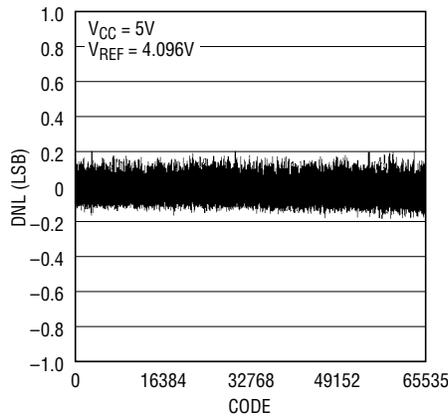
# TYPICAL PERFORMANCE CHARACTERISTICS

## LTC2605

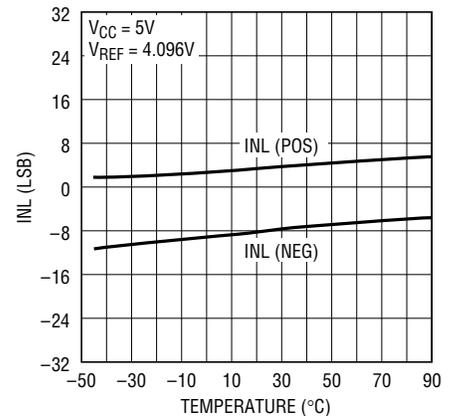
Integral Nonlinearity (INL)



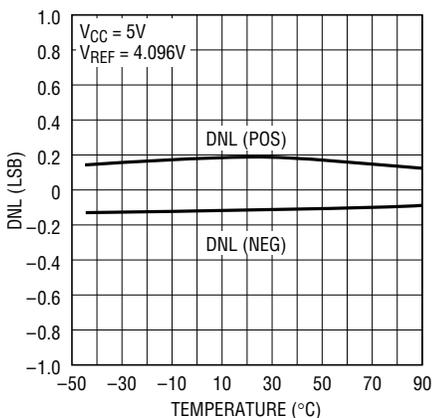
Differential Nonlinearity (DNL)



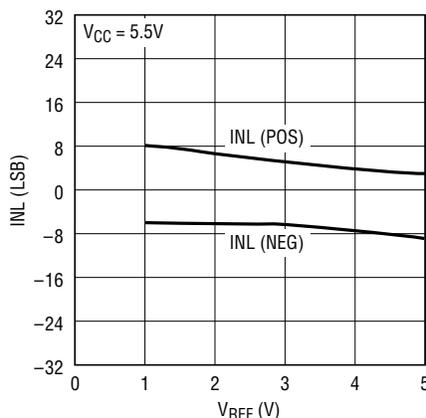
INL vs Temperature



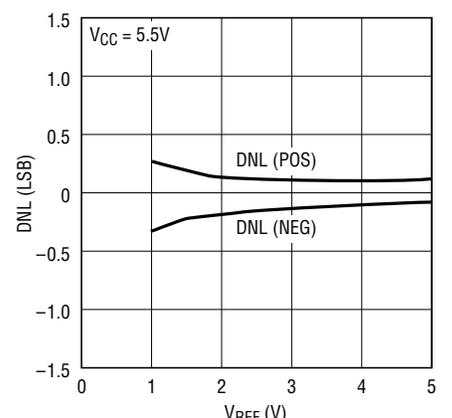
DNL vs Temperature



INL vs V\_{REF}



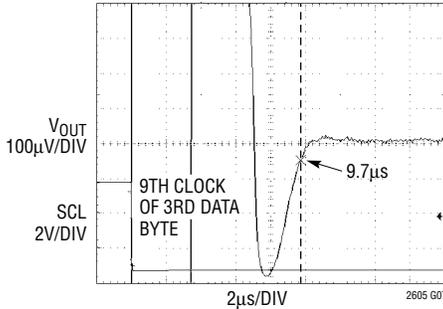
DNL vs V\_{REF}



## TYPICAL PERFORMANCE CHARACTERISTICS

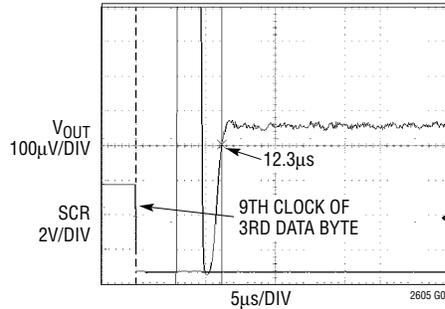
### LTC2605

Settling to  $\pm 1$ LSB



$V_{CC} = 5V$ ,  $V_{REF} = 4.096V$   
 1/4-SCALE TO 3/4-SCALE STEP  
 $R_L = 2k$ ,  $C_L = 200pF$   
 AVERAGE OF 2048 EVENTS

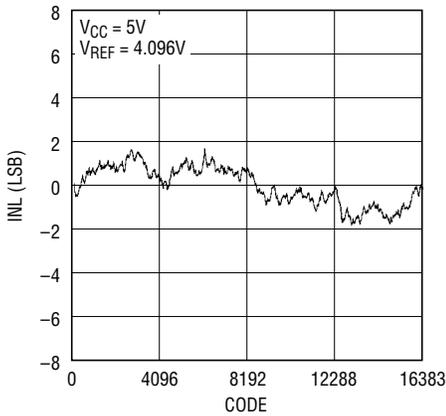
Settling of Full-Scale Step



SETTLING TO  $\pm 1$ LSB  
 $V_{CC} = 5V$ ,  $V_{REF} = 4.096V$   
 CODE 512 TO 65535 STEP  
 $R_L = 2k$ ,  $C_L = 200pF$   
 AVERAGE OF 2048 EVENTS

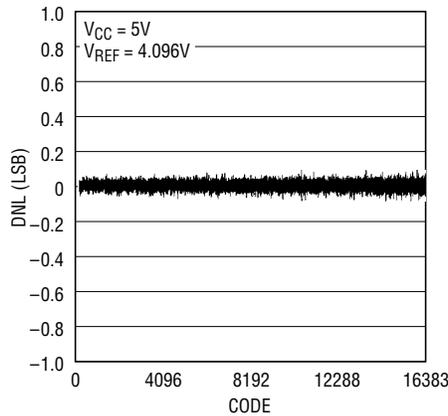
### LTC2615

Integral Nonlinearity (INL)



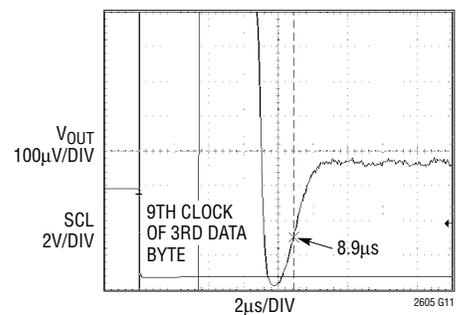
2605 G09

Differential Nonlinearity (DNL)



2605 G10

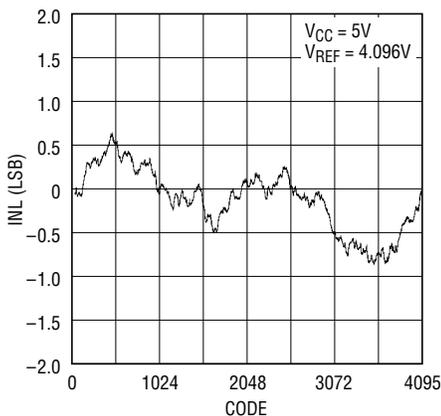
Settling to  $\pm 1$ LSB



$V_{CC} = 5V$ ,  $V_{REF} = 4.096V$   
 1/4-SCALE TO 3/4-SCALE STEP  
 $R_L = 2k$ ,  $C_L = 200pF$   
 AVERAGE OF 2048 EVENTS

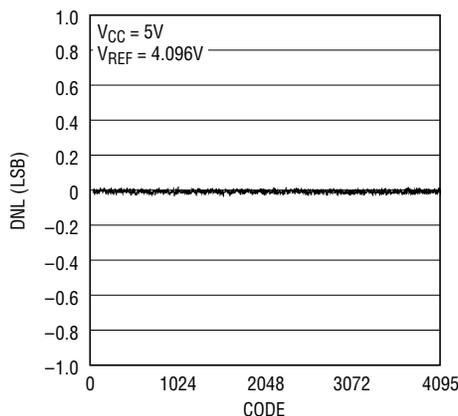
### LTC2625

Integral Nonlinearity (INL)



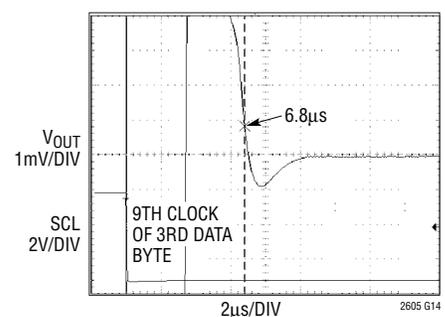
2605 G12

Differential Nonlinearity (DNL)



2605 G13

Settling to  $\pm 1$ LSB

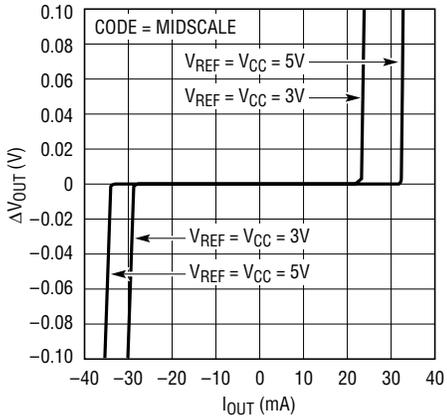


$V_{CC} = 5V$ ,  $V_{REF} = 4.096V$   
 1/4-SCALE TO 3/4-SCALE STEP  
 $R_L = 2k$ ,  $C_L = 200pF$   
 AVERAGE OF 2048 EVENTS

# TYPICAL PERFORMANCE CHARACTERISTICS

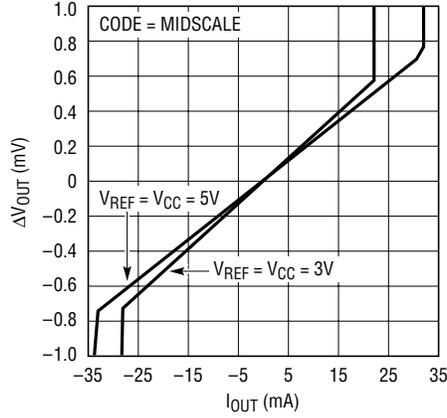
## LTC2605/LTC2615/LTC2625

**Current Limiting**



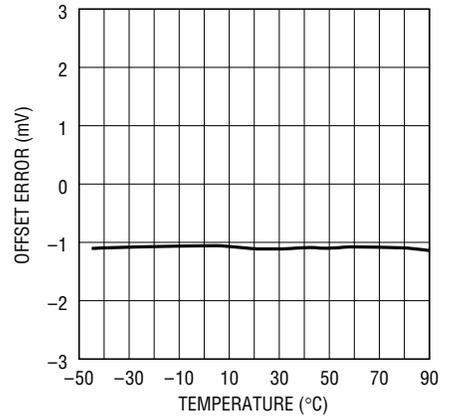
2605 G15

**Load Regulation**



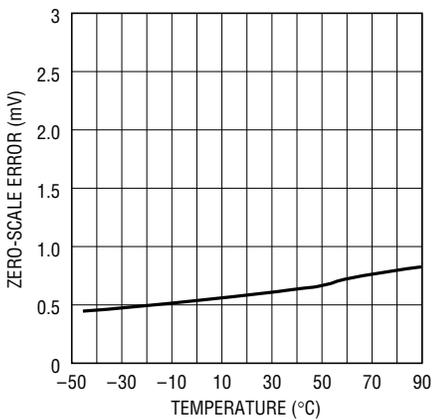
2606 G16

**Offset Error vs Temperature**



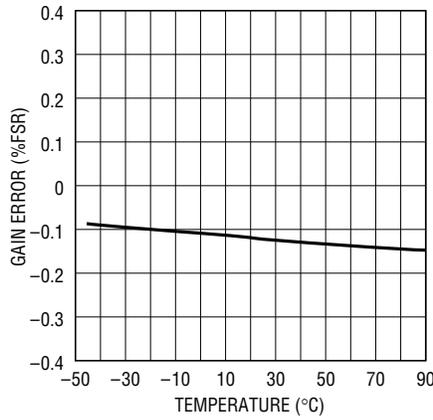
2605 G17

**Zero-Scale Error vs Temperature**



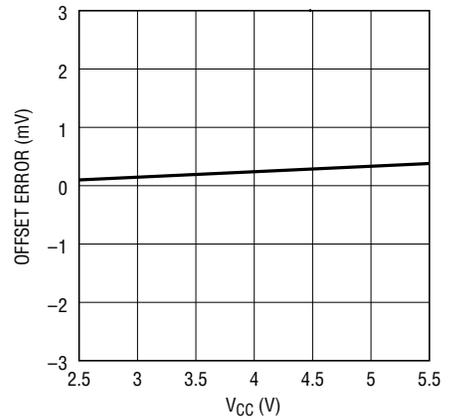
2605 G18

**Gain Error vs Temperature**



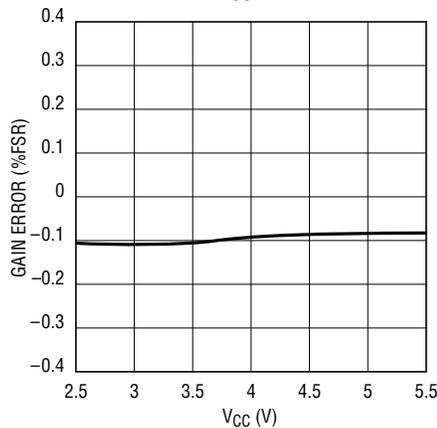
2605 G19

**Offset Error vs VCC**



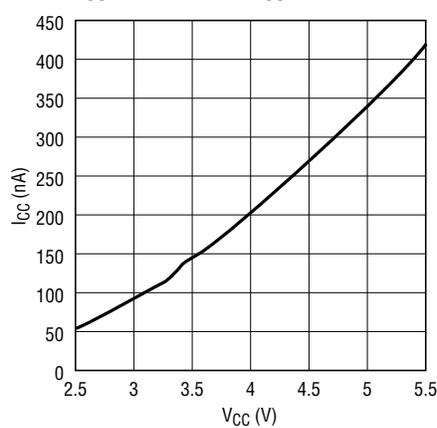
2605 G20

**Gain Error vs VCC**



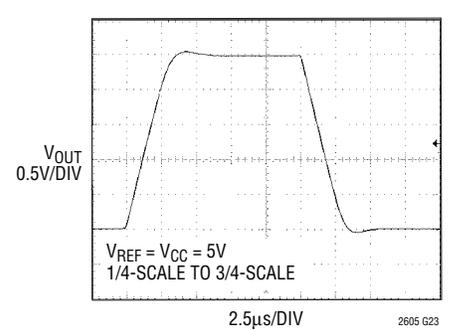
2605 G21

**ICC Shutdown vs VCC**



2605 G22

**Large-Signal Response**

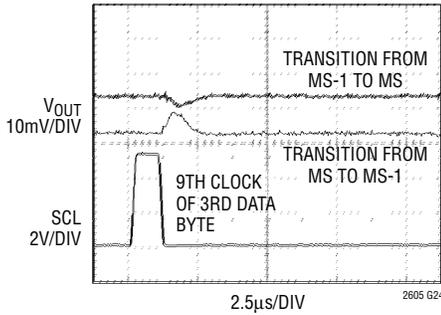


2605 G23

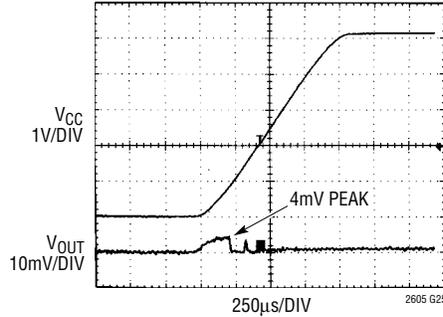
## TYPICAL PERFORMANCE CHARACTERISTICS

LTC2605/LTC2615/LTC2625

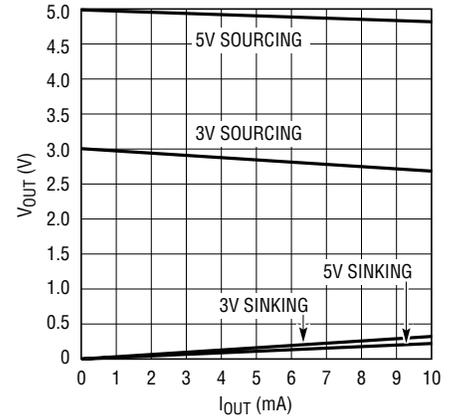
**Midscale Glitch Impulse**



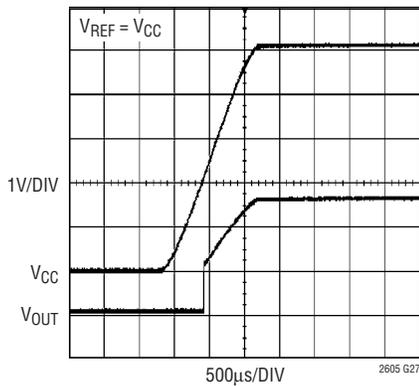
**Power-On Reset Glitch**



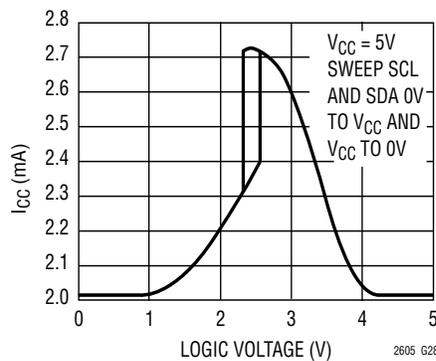
**Headroom at Rails vs Output Current**



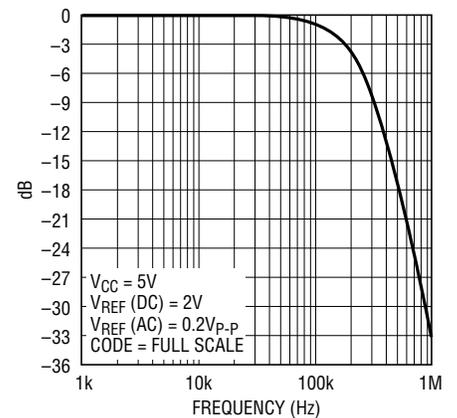
**Power-On Reset to Midscale**



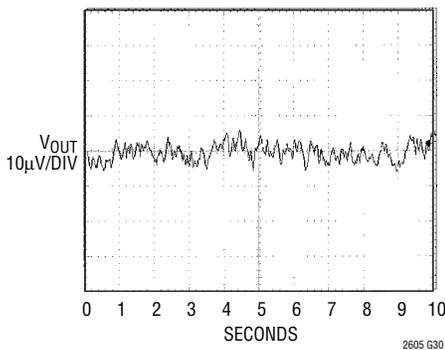
**Supply Current vs Logic Voltage**



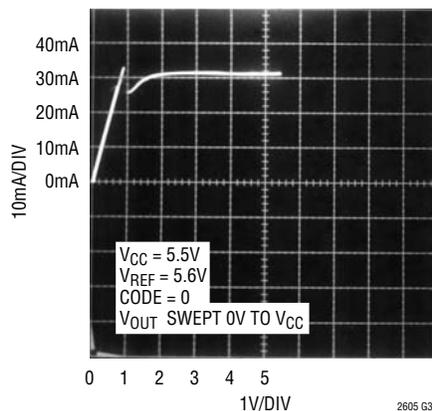
**Multiplying Bandwidth**



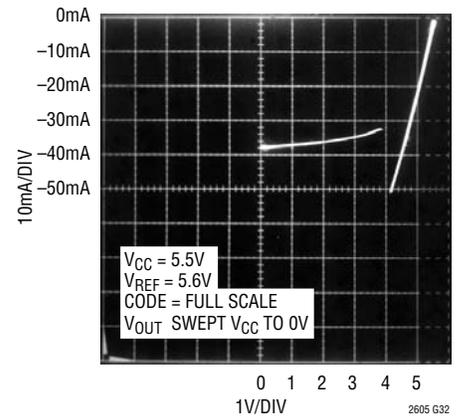
**Output Voltage Noise, 0.1Hz to 10Hz**



**Short-Circuit Output Current vs VOUT (Sinking)**



**Short-Circuit Output Current vs VOUT (Sourcing)**



## PIN FUNCTIONS

**GND (Pin 1):** Analog Ground.

**V<sub>OUT A</sub> to V<sub>OUT H</sub> (Pins 2-5 and 12-15):** DAC Analog Voltage Output. The output range is 0V to V<sub>REF</sub>.

**REF (Pin 6):** Reference Voltage Input.  $0V \leq V_{REF} \leq V_{CC}$ .

**CA2 (Pin 7):** Chip Address Bit 2. Tie this pin to V<sub>CC</sub>, GND or leave it floating to select an I<sup>2</sup>C slave address for the part (Table 2).

**SCL (Pin 8):** Serial Clock Input Pin. Data is shifted into the SDA pin at the rising edges of the clock. This high impedance pin requires a pull-up resistor or current source to V<sub>CC</sub>.

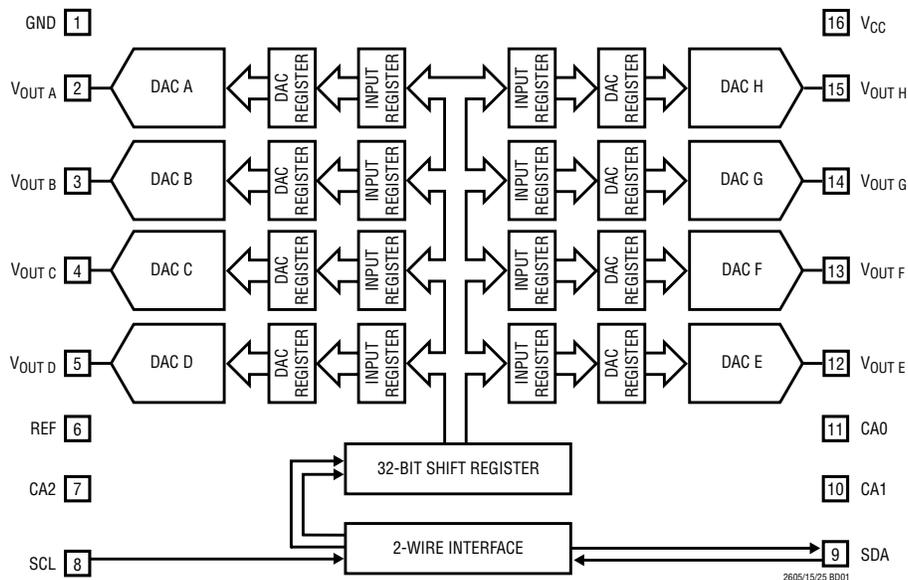
**SDA (Pin 9):** Serial Data Bidirectional Pin. Data is shifted into the SDA pin and acknowledged by the SDA pin. This is a high impedance pin while data is shifted in. It is an open-drain N-channel output during acknowledgment. This pin requires a pull-up resistor or current source to V<sub>CC</sub>.

**CA1 (Pin 10):** Chip Address Bit 1. Tie this pin to V<sub>CC</sub>, GND or leave it floating to select an I<sup>2</sup>C slave address for the part (Table 2).

**CA0 (Pin 11):** Chip Address Bit 0. Tie this pin to V<sub>CC</sub>, GND or leave it floating to select an I<sup>2</sup>C slave address for the part (Table 2).

**V<sub>CC</sub> (Pin 16):** Supply Voltage Input.  $2.7V \leq V_{CC} \leq 5.5V$ .

## BLOCK DIAGRAM



## TIMING DIAGRAM

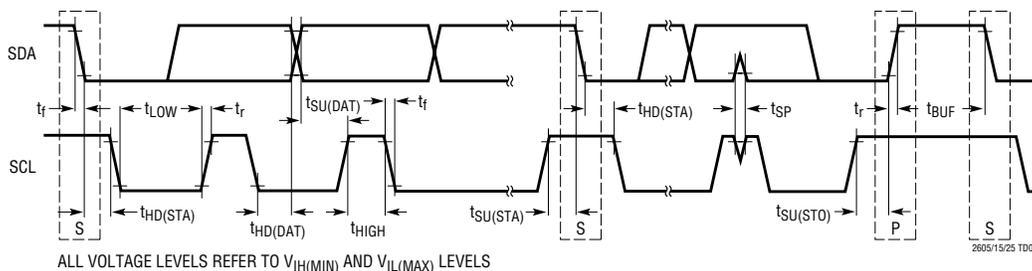


Figure 1

## OPERATION

### Power-On Reset

The LTC2605/LTC2615/LTC2625 clear the outputs to zero scale when power is first applied, making system initialization consistent and repeatable. The LTC2605-1/LTC2615-1/LTC2625-1 set the voltage outputs to midscale when power is first applied.

For some applications, downstream circuits are active during DAC power-up, and may be sensitive to nonzero outputs from the DAC during this time. The LTC2605/LTC2615/LTC2625 contain circuitry to reduce the power-on glitch: the analog outputs typically rise less than 10mV above zero scale during power on if the power supply is ramped to 5V in 1ms or more. In general, the glitch amplitude decreases as the power supply ramp time is increased. See Power-On Reset Glitch in the Typical Performance Characteristics section.

### Power Supply Sequencing

The voltage at REF (Pin 6) should be kept within the range  $-0.3V \leq V_{REF} \leq V_{CC} + 0.3V$  (see Absolute Maximum Ratings). Particular care should be taken to observe these limits during power supply turn-on and turn-off sequences, when the voltage at  $V_{CC}$  (Pin 16) is in transition.

### Transfer Function

The digital-to-analog transfer function is

$$V_{OUT(IDEAL)} = \left( \frac{k}{2^N} \right) V_{REF}$$

where  $k$  is the decimal equivalent of the binary DAC input code,  $N$  is the resolution and  $V_{REF}$  is the voltage at REF (Pin 6).

### Serial Digital Interface

The LTC2605/LTC2615/LTC2625 communicate with a host using the standard 2-wire digital interface. The Timing Diagram (Figure 1) shows the timing relationship of the signals on the bus. The two bus lines, SDA and SCL, must be high when the bus is not in use. External pull-up resistors or current sources are required on these lines. The value of these pull-up resistors is dependent on the power supply and can be obtained from the I<sup>2</sup>C specifications. For an I<sup>2</sup>C bus operating in the fast mode, an active pull-up will be necessary if the bus capacitance is greater than 200pF.

The LTC2605/LTC2615/LTC2625 are receive-only (slave) devices. The master can write to the LTC2605/LTC2615/LTC2625. The LTC2605/LTC2615/LTC2625 do not respond to a read from the master.

### The START (S) and STOP (P) Conditions

When the bus is not in use, both SCL and SDA must be high. A bus master signals the beginning of a communication to a slave device by transmitting a START condition. A START condition is generated by transitioning SDA from high to low while SCL is high.

When the master has finished communicating with the slave, it issues a STOP condition. A STOP condition is generated by transitioning SDA from low to high while SCL is high. The bus is then free for communication with another I<sup>2</sup>C device.

Table 1.

COMMAND*				
C3	C2	C1	C0	
0	0	0	0	Write to Input Register n
0	0	0	1	Update (Power Up) DAC Register n
0	0	1	0	Write to Input Register n, Update (Power Up) All n
0	0	1	1	Write to and Update (Power Up) n
0	1	0	0	Power Down n
1	1	1	1	No Operation

\*Address and command codes not shown are reserved and should not be used.

ADDRESS (n)*				
A3	A2	A1	A0	
0	0	0	0	DAC A
0	0	0	1	DAC B
0	0	1	0	DAC C
0	0	1	1	DAC D
0	1	0	0	DAC E
0	1	0	1	DAC F
0	1	1	0	DAC G
0	1	1	1	DAC H
1	1	1	1	All DACs

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## OPERATION

The command (C3-C0) and address (A3-A0) assignments are shown in Table 1. The first four commands in the table consist of write and update operations. A write operation loads the 16-bit data word from the 32-bit shift register into the input register of the selected DAC, n. An update operation copies the data word from the input register to the DAC register. Once copied into the DAC register, the data word becomes the active 16-, 14- or 12-bit input code, and is converted to an analog voltage at the DAC output. The update operation also powers up the selected DAC if it had been in power-down mode. The data path and registers are shown in the block diagram.

**Table 2. Slave Address Map**

CA2	CA1	CA0	SA6	SA5	SA4	SA3	SA2	SA1	SA0
GND	GND	GND	0	0	1	0	0	0	0
GND	GND	FLOAT	0	0	1	0	0	0	1
GND	GND	V <sub>CC</sub>	0	0	1	0	0	1	0
GND	FLOAT	GND	0	0	1	0	0	1	1
GND	FLOAT	FLOAT	0	1	0	0	0	0	0
GND	FLOAT	V <sub>CC</sub>	0	1	0	0	0	0	1
GND	V <sub>CC</sub>	GND	0	1	0	0	0	1	0
GND	V <sub>CC</sub>	FLOAT	0	1	0	0	0	1	1
GND	V <sub>CC</sub>	V <sub>CC</sub>	0	1	1	0	0	0	0
FLOAT	GND	GND	0	1	1	0	0	0	1
FLOAT	GND	FLOAT	0	1	1	0	0	1	0
FLOAT	GND	V <sub>CC</sub>	0	1	1	0	0	1	1
FLOAT	FLOAT	GND	1	0	0	0	0	0	0
FLOAT	FLOAT	FLOAT	1	0	0	0	0	0	1
FLOAT	FLOAT	V <sub>CC</sub>	1	0	0	0	0	1	0
FLOAT	V <sub>CC</sub>	GND	1	0	0	0	0	1	1
FLOAT	V <sub>CC</sub>	FLOAT	1	0	1	0	0	0	0
FLOAT	V <sub>CC</sub>	V <sub>CC</sub>	1	0	1	0	0	0	1
V <sub>CC</sub>	GND	GND	1	0	1	0	0	1	0
V <sub>CC</sub>	GND	FLOAT	1	0	1	0	0	1	1
V <sub>CC</sub>	GND	V <sub>CC</sub>	1	1	0	0	0	0	0
V <sub>CC</sub>	FLOAT	GND	1	1	0	0	0	0	1
V <sub>CC</sub>	FLOAT	FLOAT	1	1	0	0	0	1	0
V <sub>CC</sub>	FLOAT	V <sub>CC</sub>	1	1	0	0	0	1	1
V <sub>CC</sub>	V <sub>CC</sub>	GND	1	1	1	0	0	0	0
V <sub>CC</sub>	V <sub>CC</sub>	FLOAT	1	1	1	0	0	0	1
V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	1	1	1	0	0	1	0
GLOBAL ADDRESS			1	1	1	0	0	1	1

### Power Down Mode

For power-constrained applications, power-down mode can be used to reduce the supply current whenever less than eight outputs are needed. When in power-down, the buffer amplifiers and reference inputs are disabled and draw essentially zero current. The DAC outputs are put into a high-impedance state, and the output pins are passively pulled to ground through individual 90k resistors. When all eight DACs are powered down, the bias generation circuit is also disabled. Input- and DAC- registers are not disturbed during power-down.

Any channel or combination of channels can be put into power-down mode by using command 0100<sub>b</sub> in combination with the appropriate DAC address, (n). The 16-bit data word is ignored. The supply and reference currents are reduced by approximately 1/8 for each DAC powered down; the effective resistance at REF (Pin 6) rises accordingly, becoming a high-impedance input (typically >1GΩ) when all eight DACs are powered down.

Normal operation can be resumed by executing any command which includes a DAC update, as shown in Table 1. The selected DAC is powered up as its voltage output is updated.

There is an initial delay as the DAC powers up before it begins its usual settling behavior. If less than eight DACs are in a powered-down state prior to the updated command, the power-up delay is 5μs. If, on the other hand, all eight DACs are powered down, then the bias generation circuit is also disabled and must be restarted. In this case, the power-up delay is greater: 12μs for V<sub>CC</sub> = 5V, 30μs for V<sub>CC</sub> = 3V.

### Voltage Outputs

Each of the eight rail-to-rail amplifiers contained in these parts has guaranteed load regulation when sourcing or sinking up to 15mA at 5V (7.5mA at 3V).

Load regulation is a measure of the amplifier's ability to maintain the rated voltage accuracy over a wide range of load conditions. The measured change in output voltage per milliampere of forced load current change is expressed in LSB/mA.

## OPERATION

DC output impedance is equivalent to load regulation and may be derived from it by simply calculating a change in units from LSB/mA to Ohms. The amplifier's DC output impedance is  $0.020\Omega$  when driving a load well away from the rails.

When drawing a load current from either rail, the output voltage headroom with respect to that rail is limited by the  $30\Omega$  typical channel resistance of the output devices; e.g., when sinking 1mA, the minimum output voltage =  $30\Omega \cdot 1\text{mA} = 30\text{mV}$ . See the graph Headroom at Rails vs Output Current in the Typical Performance Characteristics section.

The amplifiers are stable driving capacitive loads of up to 1000pF.

### Board Layout

The excellent load regulation and DC crosstalk performance of these devices is achieved in part by keeping "signal" and "power" grounds separated internally and by reducing shared internal resistance to just  $0.005\Omega$ .

The GND pin functions both as the node to which the reference and output voltages are referred and as a return path for power currents in the device. Because of this, careful thought should be given to the grounding scheme and board layout in order to ensure rated performance.

The PC board should have separate areas for the analog and digital sections of the circuit. This keeps digital signals away from sensitive analog signals and facilitates the use of separate digital and analog ground planes which have minimal capacitive and resistive interaction with each other.

Digital and analog ground planes should be joined at only one point, establishing a system star ground as close to the device's ground pin as possible. Ideally, the analog ground plane should be located on the component side of the board, and should be allowed to run under the part to shield it from noise. Analog ground should be a continuous and uninterrupted plane, except for necessary lead pads and vias, with signal traces on another layer.

The GND pin of the part should be connected to analog ground. Resistance from the GND pin to system star ground should be as low as possible. Resistance here will add directly to the effective DC output impedance of the device (typically  $0.020\Omega$ ), and will degrade DC crosstalk. Note that the LTC2605/LTC2615/LTC2625 are no more susceptible to these effects than other parts of their type; on the contrary, they allow layout-based performance improvements to shine rather than limiting attainable performance with excessive internal resistance.

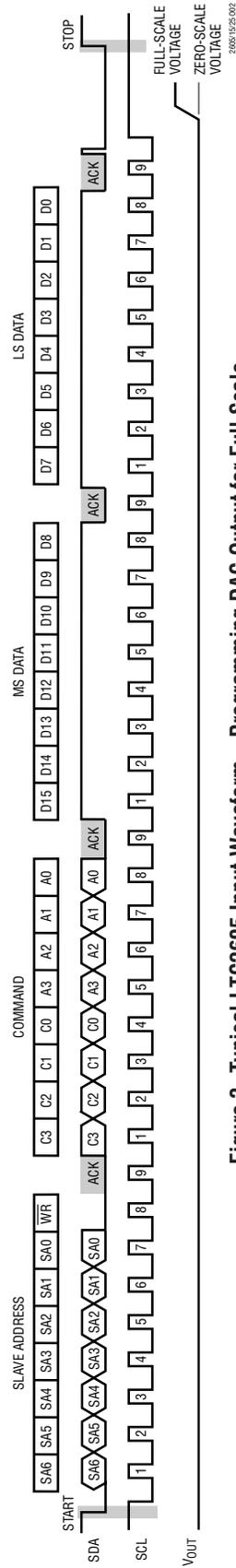
### Rail-to-Rail Output Considerations

In any rail-to-rail voltage output device, the output is limited to voltages within the supply range.

Since the analog outputs of the device cannot go below ground, they may limit for the lowest codes as shown in Figure 4b. Similarly, limiting can occur near full scale when the REF pin is tied to  $V_{CC}$ . If  $V_{REF} = V_{CC}$  and the DAC full-scale error (FSE) is positive, the output for the highest codes limits at  $V_{CC}$  as shown in Figure 4c. No full-scale limiting can occur if  $V_{REF}$  is less than  $V_{CC} - \text{FSE}$ .

Offset and linearity are defined and tested over the region of the DAC transfer function where no output limiting can occur.

**OPERATION**



**Figure 3. Typical LTC2605 Input Waveform—Programming DAC Output for Full Scale**

# OPERATION

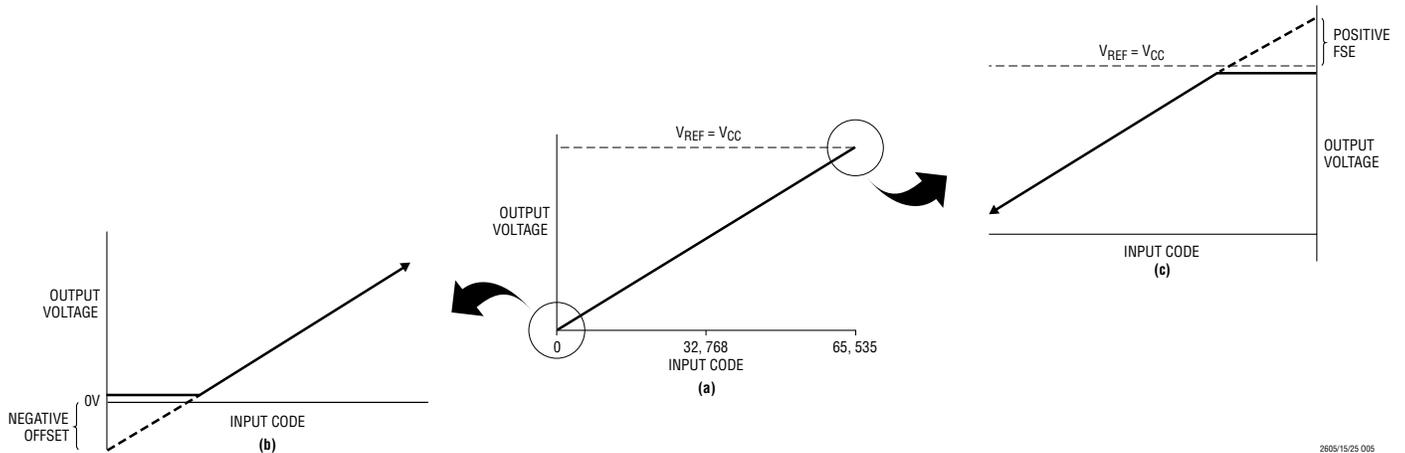
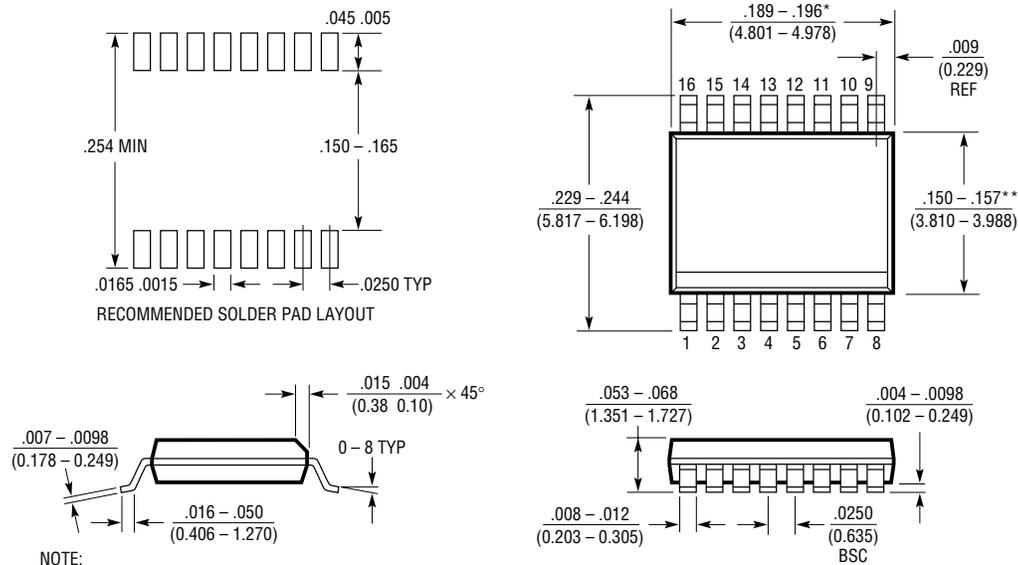


Figure 4. Effects of Rail-to-Rail Operation on a DAC Transfer Curve. (a) Overall Transfer Function, (b) Effect of Negative Offset for Codes Near Zero Scale, (c) Effect of Positive Full-Scale Error for Codes Near Full Scale

# PACKAGE DESCRIPTION

## GN Package 16-Lead Plastic SSOP (Narrow .150 Inch) (Reference LTC DWG # 05-08-1641)

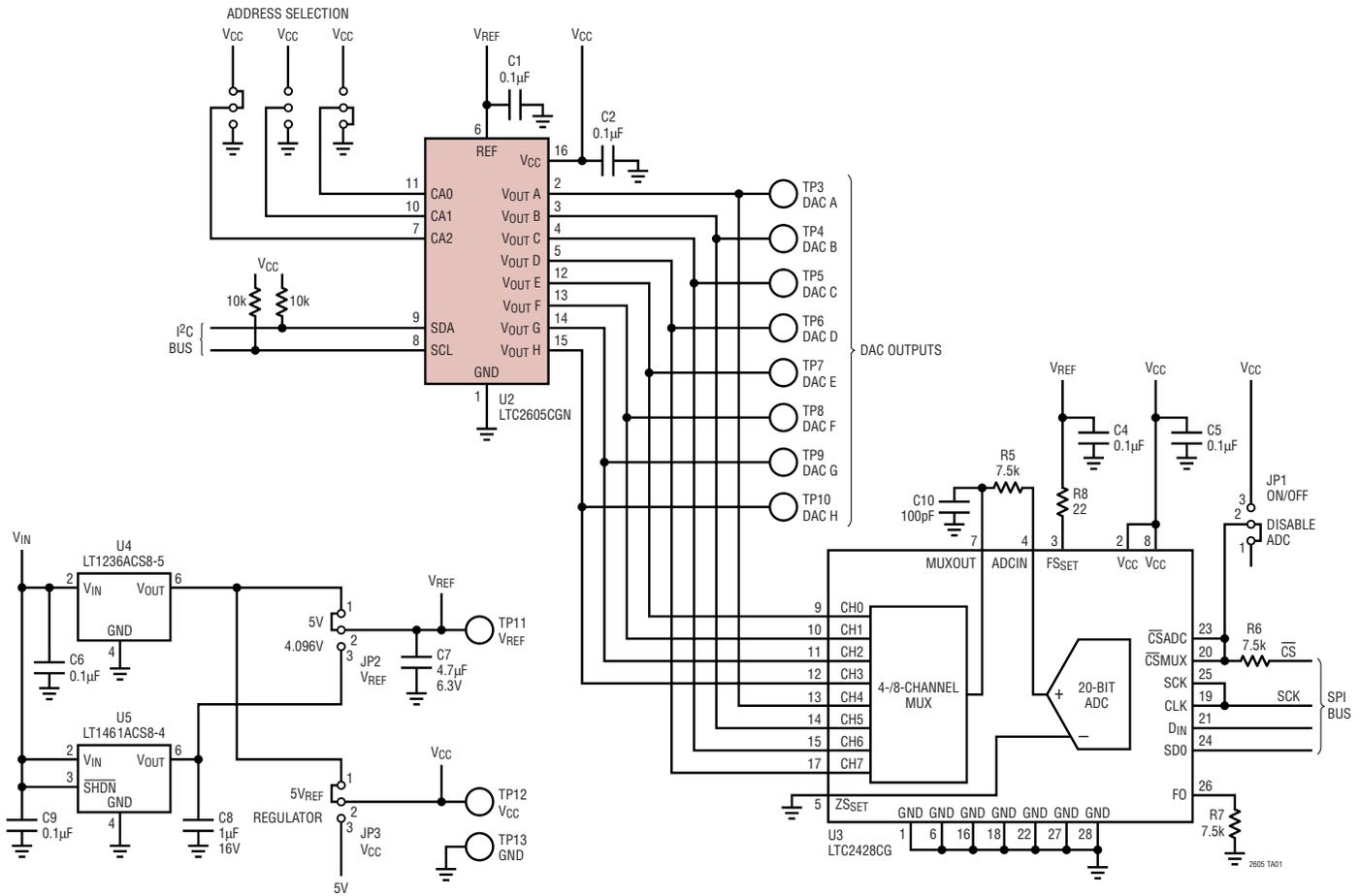


- NOTE:
1. CONTROLLING DIMENSION: INCHES
  2. DIMENSIONS ARE IN  $\frac{\text{INCHES}}{\text{MILLIMETERS}}$
  3. DRAWING NOT TO SCALE
- \*DIMENSION DOES NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.006" (0.152mm) PER SIDE
- \*\*DIMENSION DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" (0.254mm) PER SIDE

GN16 (SSOP) 0502

# TYPICAL APPLICATION

Demonstration Circuit—LTC2428 20-Bit ADC Measures Key Performance Parameters



## RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC1458/LTC1458L	Quad 12-Bit Rail-to-Rail Output DACs with Added Functionality	LTC1458: $V_{CC} = 4.5V$ to $5.5V$ , $V_{OUT} = 0V$ to $4.096V$ LTC1458L: $V_{CC} = 2.7V$ to $5.5V$ , $V_{OUT} = 0V$ to $2.5V$
LTC1654	Dual 14-Bit Rail-to-Rail $V_{OUT}$ DAC	Programmable Speed/Power, $3.5\mu s/750\mu A$ , $8\mu s/450\mu A$
LTC1655/LTC1655L	Single 16-Bit $V_{OUT}$ DAC with Serial Interface in SO-8	$V_{CC} = 5V(3V)$ , Low Power, Deglitched
LTC1657/LTC1657L	Parallel 5V/3V 16-Bit $V_{OUT}$ DAC	Low Power, Deglitched, Rail-to-Rail $V_{OUT}$
LTC1660/LTC1665	Octal 10-/8-Bit $V_{OUT}$ DAC in 16-Pin Narrow SSOP	$V_{CC} = 2.7V$ to $5.5V$ , Micropower, Rail-to-Rail Output
LTC1821	Parallel 16-Bit Voltage Output DAC	Precision 16-Bit Settling in $2\mu s$ for 10V Step
LTC2600/LTC2610/ LTC2620	Octal 16-/14-/12-Bit $V_{OUT}$ DACs in 16-Lead SSOP	$250\mu A$ per DAC, $2.5V$ – $5.5V$ Supply Range, Rail-to-Rail Output, SPI Interface
LTC2601/LTC2611/ LTC2621	Single 16-/14-/12-Bit $V_{OUT}$ DACs in 10-Lead DFN	$300\mu A$ per DAC, $2.5V$ – $5.5V$ Supply Range, Rail-to-Rail Output, SPI Interface
LTC2602/LTC2612/ LTC2622	Dual 16-/14-/12-Bit $V_{OUT}$ DACs in 8-Lead MSOP	$300\mu A$ per DAC, $2.5V$ – $5.5V$ Supply Range, Rail-to-Rail Output, SPI Interface
LTC2604/LTC2614/ LTC2624	Quad 16-/14-/12-Bit $V_{OUT}$ DACs in 16-Lead SSOP	$250\mu A$ per DAC, $2.5V$ – $5.5V$ Supply Range, Rail-to-Rail Output, SPI Interface
LTC2606/LTC2616/ LTC2626	Single 16-/14-/12-Bit $V_{OUT}$ DACs with I <sup>2</sup> C Interface in 10-Lead DFN	$270\mu A$ per DAC, $2.7V$ – $5.5V$ Supply Range, Rail-to-Rail Output, I <sup>2</sup> C Interface

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